54F245,74F245

54F245 74F245 Octal Bidirectional Transceiver with TRI-STATE Outputs



Literature Number: SNOS177A

54F/74F245 Octal Bidirectional Transceiver with TRI-STATE® Outputs

General Description

The 'F245 contains eight non-inverting bidirectional buffers with TRI-STATE outputs and is intended for bus-oriented applications. Current sinking capability is 24 mA (20 mA Mil) at the A ports and 64 mA (48 mA Mil) at the B ports. The Transmit/Receive (T/ $\overline{\rm R}$) input determines the direction of data flow through the bidirectional transceiver. Transmit (active HIGH) enables data from A ports to B ports; Receive (active LOW) enables data from B ports to A ports. The Output Enable input, when HIGH, disables both A and B ports by placing them in a High Z condition.

Features

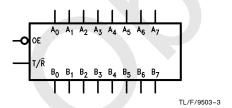
- Non-inverting buffers
- Bidirectional data path
- A outputs sink 24 mA (20 mA Mil)
- B outputs sink 64 mA (48 mA Mil)
- Guaranteed 4000V minimum ESD protection

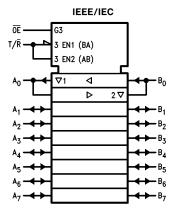
Commercial	Military	Package Number	Package Description
74F245PC		N20A	20-Lead (0.300" Wide) Molded Dual-In-Line
	54F245DM (Note 2)	J20A	20-Lead Ceramic Dual-In-Line
74F245SC (Note 1)		M20B	20-Lead (0.300" Wide) Molded Small Outline, JEDEC
74F245SJ (Note 1)		M20D	20-Lead (0.300" Wide) Molded Small Outline, EIAJ
74F245MSA (Note 1)		MSA20	20-Lead Molded Shrink Small Outline, EIAJ Type II
	54F245FM (Note 2)	W20A	20-Lead Cerpack
	54F245LM (Note 2)	E20A	20-Lead Ceramic Leadless Chip Carrier, Type C

Note 1: Devices also available in 13" reel. Use suffix = SCX, SJX and MSAX.

Note 2: Military grade device with environmental and burn-in processing. Use suffix = DMQB, FMQB and LMQB.

Logic Symbols



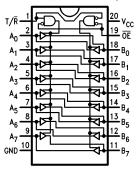


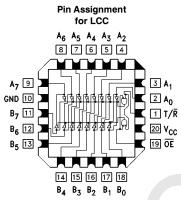
TL/F/9503-4

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Connection Diagrams

Pin Assignment for DIP, SOIC, SSOP and Flatpak





TL/F/9503-1

TL/F/9503-2

Unit Loading/Fan Out

		54F/74F				
Pin Names	Description	U.L. HIGH/LOW	Input I _{IH} /I _{IL} Output I _{OH} /I _{OL}			
ŌĒ	Output Enable Input (Active LOW)	1.0/2.0	20 μA/ – 1.2 mA			
T/R	Transmit/Receive Input	1.0/2.0	20 μA/ – 1.2 mA			
A ₀ -A ₇	Side A Inputs or	3.5/1.083	70 μA/ - 0.65 mA			
	TRI-STATE Outputs	150/40(38.3)	-3 mA/24 mA (20 mA)			
B ₀ -B ₇	Side B Inputs or	3.5/1.083	$70 \mu A/-0.65 mA$			
	TRI-STATE Outputs	600/106.6(80)	-12 mA/64 mA (48 mA)			

Truth Table

ut	Outpu	Inputs			
ui	Catpa	T/R	ŌĒ		
to Bus A	Bus B Data to	L	L		
to Bus B	Bus A Data to	Н	L		
е	High Z State	X	I н		

 $\begin{array}{l} H = \mbox{HIGH Voltage Level} \\ L = \mbox{LOW Voltage Level} \\ X = \mbox{Immaterial} \end{array}$

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

 $\begin{array}{lll} \text{Storage Temperature} & -65^{\circ}\text{C to} + 150^{\circ}\text{C} \\ \text{Ambient Temperature under Bias} & -55^{\circ}\text{C to} + 125^{\circ}\text{C} \\ \text{Junction Temperature under Bias} & -55^{\circ}\text{C to} + 175^{\circ}\text{C} \\ \text{Plastic} & -55^{\circ}\text{C to} + 150^{\circ}\text{C} \\ \end{array}$

V_{CC} Pin Potential to

Ground Pin -0.5V to +7.0V Input Voltage (Note 2) -0.5V to +7.0V

Input Current (Note 2) -30 mA to +5.0 mA

Voltage Applied to Output

in HIGH State (with $V_{CC} = 0V$)

 $\begin{array}{lll} \text{Standard Output} & -0.5 \text{V to V}_{\text{CC}} \\ \text{TRI-STATE Output} & -0.5 \text{V to } +5.5 \text{V} \end{array}$

Current Applied to Output

in LOW State (Max) ${\rm twice\ the\ rated\ I_{OL}\ (mA)}$ ESD Last Passing Voltage (Min) ${\rm 4000V}$

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

Recommended Operating Conditions

Free Air Ambient Temperature

Supply Voltage

Military + 4.5V to + 5.5V Commercial + 4.5V to + 5.5V

DC Electrical Characteristics

Symbol	Parameter		54F/74F			Units	V	Conditions	
Syllibol			Min	Тур	Max	Units	V _{CC}	Conditions	
V _{IH}	Input HIGH Voltage		2.0			V		Recognized as a HIGH Signal	
V _{IL}	Input LOW Voltage				0.8	٧		Recognized as a LOW Signal	
V _{CD}	Input Clamp Diode \	/oltage			-1.2	V	Min	$I_{\text{IN}} = -18 \text{mA}$	
V _{OH}	Output HIGH Voltage	54F 10% V _{CC} 54F 10% V _{CC} 74F 10% V _{CC} 74F 10% V _{CC} 74F 5% V _{CC}	2.4 2.0 2.4 2.0 2.7			V	Min	$\begin{split} I_{OH} &= -3 \text{ mA } (A_n) \\ I_{OH} &= -12 \text{ mA } (B_n) \\ I_{OH} &= -3 \text{ mA } (A_n) \\ I_{OH} &= -15 \text{ mA } (B_n) \\ I_{OH} &= -3 \text{ mA } (A_n) \end{split}$	
V _{OL}	Output LOW Voltage	54F 10% V _{CC} 54F 10% V _{CC} 74F 10% V _{CC} 74F 10% V _{CC}			0.5 0.55 0.5 0.55	V	Min	I _{OL} = 20 mA (A _n) I _{OL} = 48 mA (B _n) I _{OL} = 24 mA (A _n) I _{OL} = 64 mA (B _n)	
I _{IH}	Input HIGH Current	54F 74F			20.0 5.0	μΑ	Max	V _{IN} = 2.7V	
I _{BVI}	Input HIGH Current Breakdown Test	54F 74F			100 7.0	μΑ	Max	$V_{IN} = 7.0V (\overline{OE}, T/\overline{R})$	
I _{BVIT}	Input HIGH Current Breakdown (I/O)	54F 74F			1.0 0.5	mA	Max	$V_{IN} = 5.5 \text{ V } (A_n, B_n)$	
I _{CEX}	Output HIGH Leakage Current	54F 74F			250 50	μΑ	Max	$V_{OUT} = V_{CC} (A_n, B_n)$	
V_{ID}	Input Leakage Test	74F	4.75			٧	0.0	$I_{\text{ID}} = 1.9 \mu\text{A}$ All Other Pins Grounded	
I _{OD}	Output Leakage Circuit Current	74F			3.75	μΑ	0.0	V _{IOD} = 150 mV All Other Pins Grounded	
I _{IL}	Input LOW Current				-1.2	mA	Max	$V_{IN} = 0.5V (T/\overline{R}, \overline{OE})$	
I _{IH} + I _{OZH}	Output Leakage Current				70	μΑ	Max	$V_{OUT} = 2.7V (A_n, B_n)$	
I _{IL} + I _{OZL}	Output Leakage Current				-650	μΑ	Max	$V_{OUT} = 0.5V (A_n, B_n)$	

DC Electrical Characteristics (Continued)

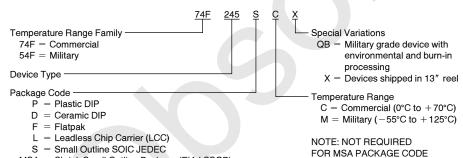
Symbol	Parameter	54F/74F			Units	V _{CC}	Conditions	
Symbol	i didilictei	Min	Тур	Max	Omis	•66	33	
los	Output Short-Circuit Current	-60 -100		−150 −225	mA	Max	$V_{OUT} = 0V (A_n)$ $V_{OUT} = 0V (B_n)$	
I_{ZZ}	Bus Drainage Test			500	μΑ	0.0V	$V_{OUT} = 5.25V(A_n, B_n)$	
Icch	Power Supply Current		70	90	mA	Max	V _O = HIGH	
I _{CCL}	Power Supply Current		95	120	mA	Max	$V_O = LOW$	
I _{CCZ}	Power Supply Current		85	110	mA	Max	V _O = HIGH Z	

AC Electrical Characteristics

		74F			5-	4F	74F		
Symbol Parameter		$\begin{aligned} \textbf{T}_{\textbf{A}} &= +25^{\circ}\textbf{C} \\ \textbf{V}_{\textbf{CC}} &= +5.0\textbf{V} \\ \textbf{C}_{\textbf{L}} &= 50\textbf{pF} \end{aligned}$			$ extsf{T}_{ extsf{A}}, extsf{V}_{ extsf{CC}} = extsf{Mil} \ extsf{C}_{ extsf{L}} = extsf{50 pF}$		T _A , V _{CC} = Com C _L = 50 pF		Units
		Min	Тур	Max	Min	Max	Min	Max	
t _{PLH}	Propagation Delay A _n to B _n or B _n to A _n	2.5 2.5	4.2 4.2	6.0 6.0	2.0 2.0	7.5 7.5	2.0 2.0	7.0 7.0	ns
t _{PZH}	Output Enable Time	3.0 3.5	5.3 6.0	7.0 8.0	2.5 3.0	9.0 10.0	2.5 3.0	8.0 9.0	- ns
t _{PHZ}	Output Disable Time	2.0 2.0	5.0 5.0	6.5 6.5	2.0 2.0	9.0 10.0	2.0 2.0	7.5 7.5	113

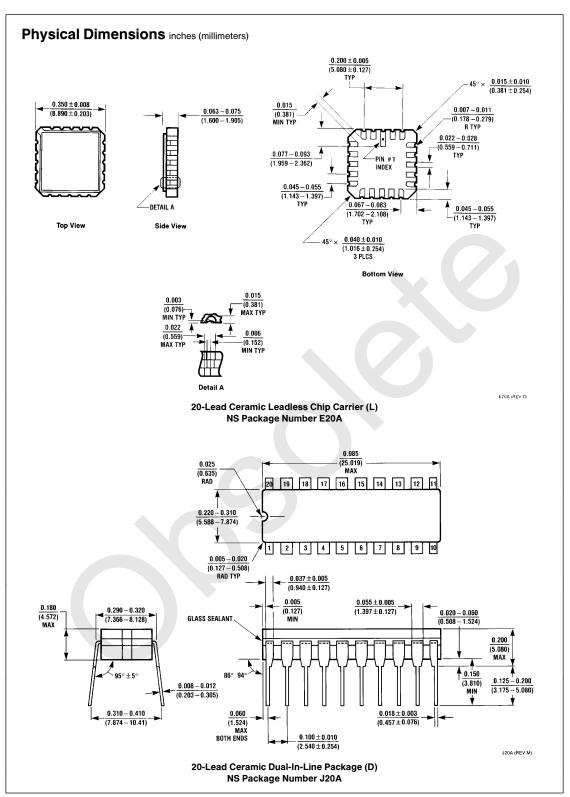
Ordering Information

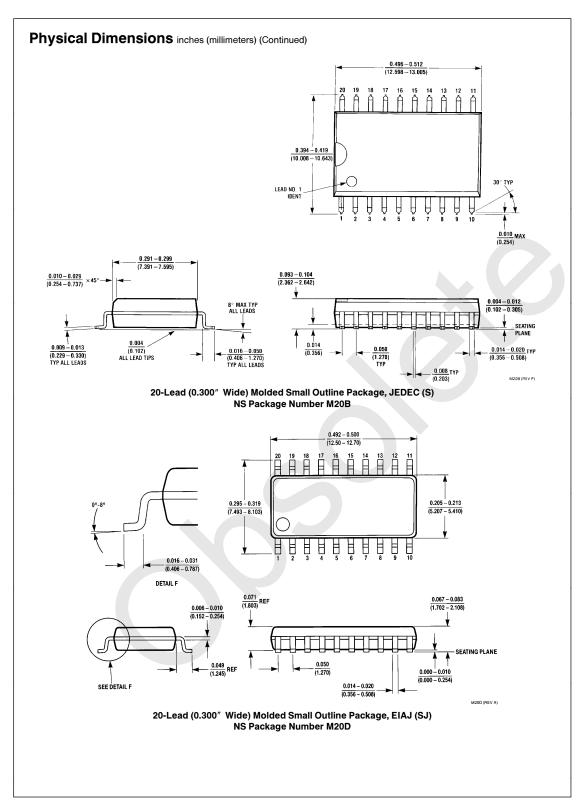
The device number is used to form part of a simplified purchasing code where the package type and temperature range are defined as follows:

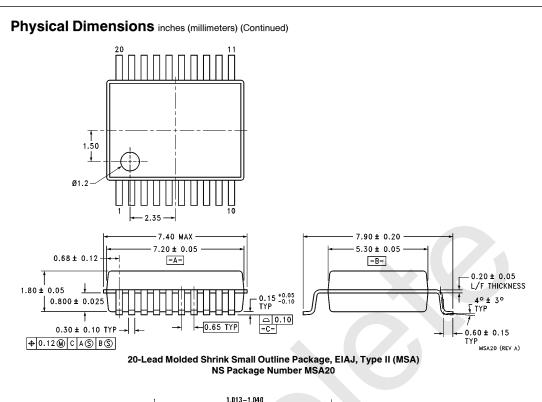


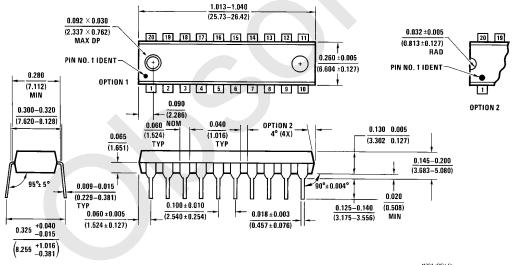
MSA = Shrink Small Outline Package (EIAJ SSOP)

SJ = Small Outline Package SOIC EIAJ



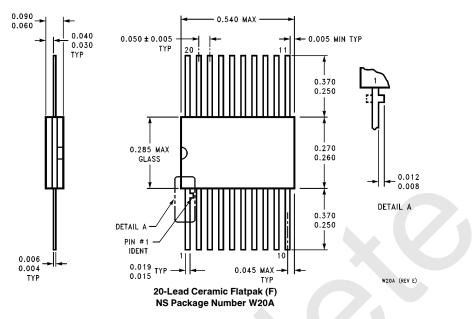






20-Lead Molded (0.300" Wide) Dual-In-Line Package (P) NS Package Number N20A

Physical Dimensions inches (millimeters) (Continued)



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